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# Microsystem & transistor fabrication on a silicon substrate

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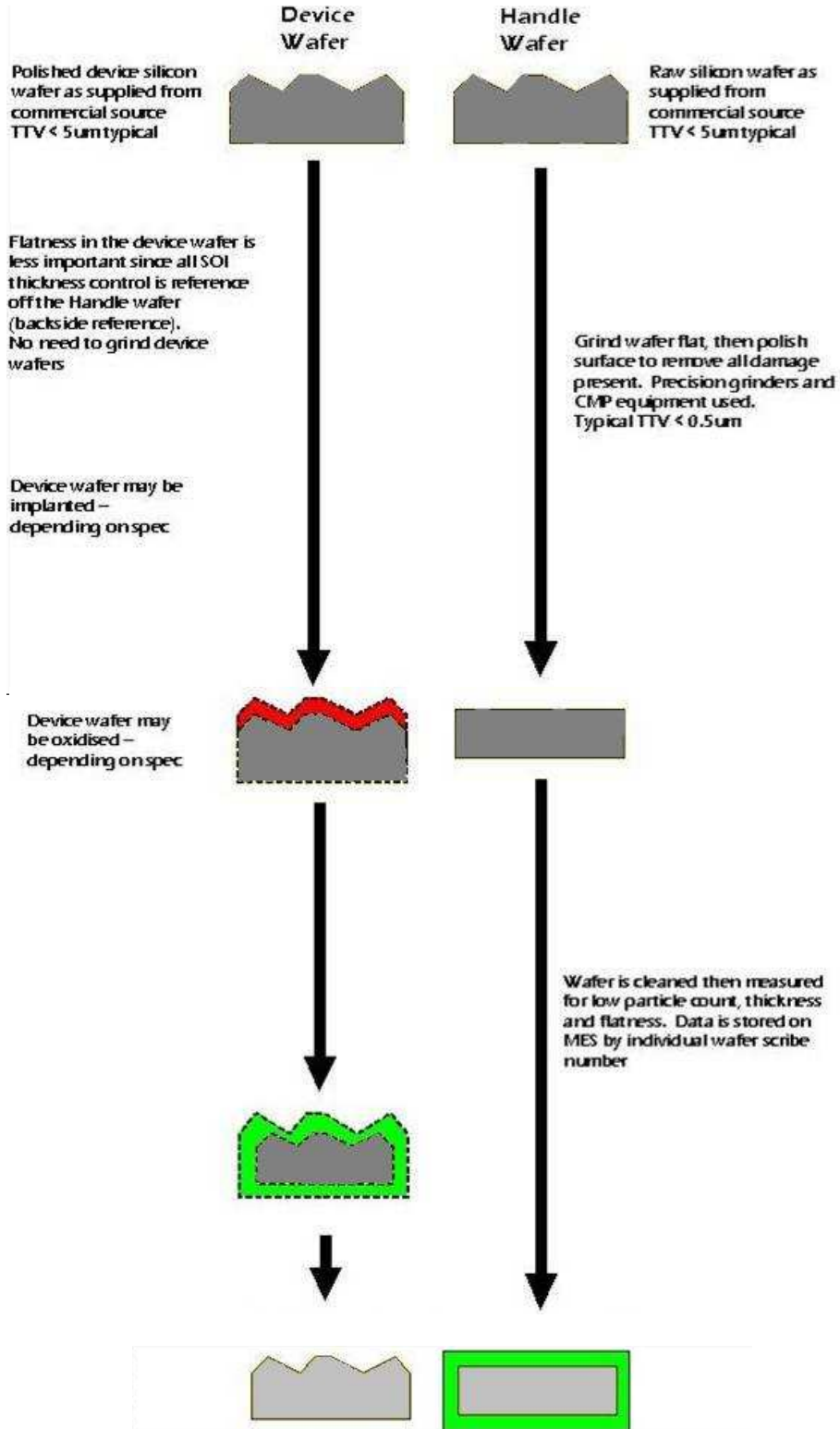
## T NMOS grille Si poly + MICROSYSTEMES: masques MEMS

<u>Organisation MEMS actuelle en 16h</u>
<p><b>Étapes sous-traitées au CIME pour préparation de plaques:</b></p> <ul style="list-style-type: none"> <li>(1) nettoyage</li> <li>(1bis) désoxydation FAR des plaques SOI</li> <li>(2) oxydation thermique humide</li> <li>(3) photolithographie</li> <li>(4) ouverture des zones actives</li> </ul>
<p><b>Étapes sous-traitées au LAAS:</b></p> <ul style="list-style-type: none"> <li>(5) Nettoyage</li> <li>(6) oxydation thermique sèche</li> <li>(7) dépôt Si poly</li> </ul>
<p><b>S1: photolithographie Si poly - RIE</b></p>
<p><b>S2: implantation</b>            Gravure oxyde en face arrière du wafer SOI avec protection de la face avant du wafer par de la résine            Retrait résine + nettoyage            Recuit d'implantation</p>
<p><b>Étape sous-traitées: désoxydation et mise sous vide pour dépôt alu</b></p>
<p><b>S3: dépôt alu – photolithographie et gravure alu</b></p>
<p><b>S4: photolithographie résine épaisse FAR - DRIE</b></p>

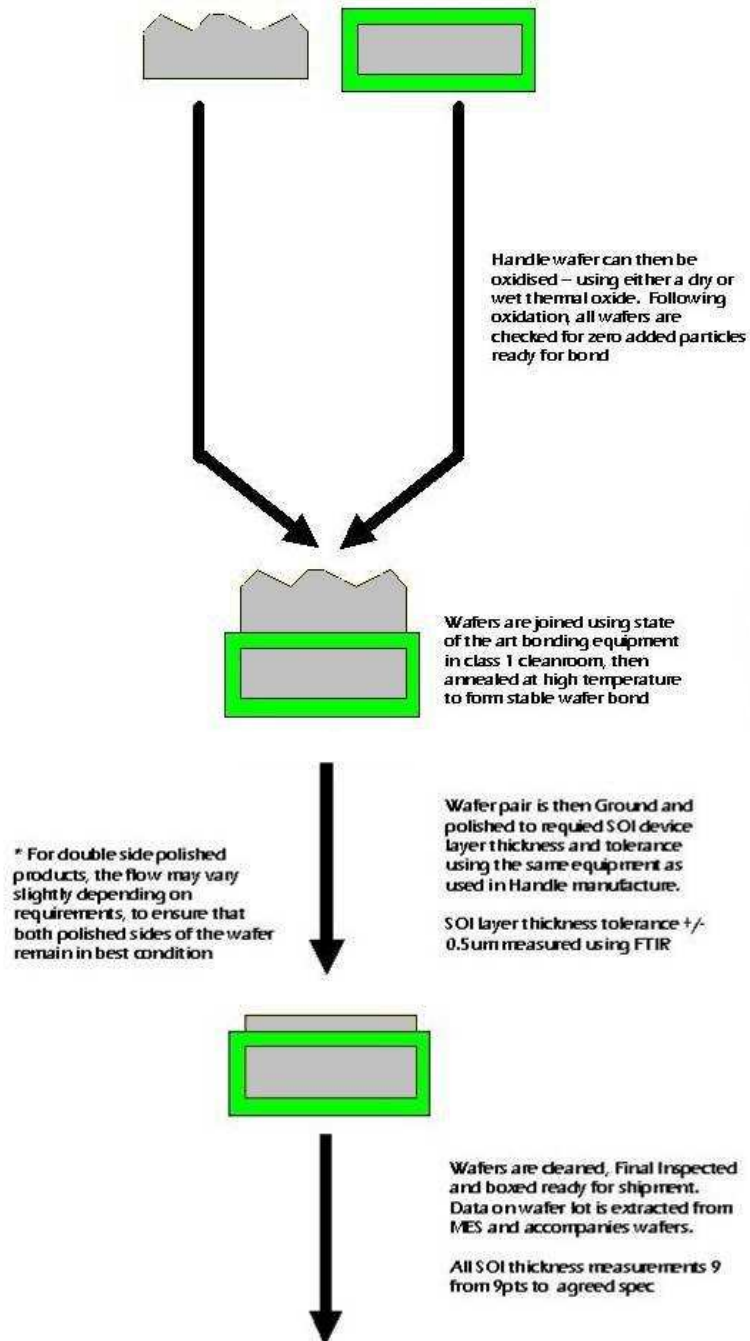
Fourniture par groupe de 4 étudiants:

- une plaque 4 pouces polies double face
- une plaque SOI

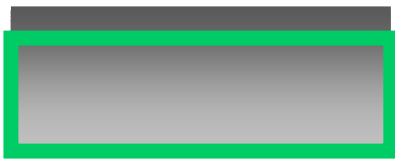
# SOI wafers



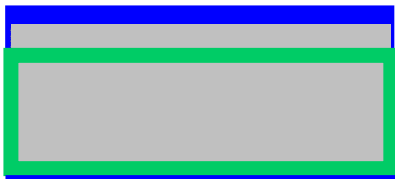
# SOI wafers



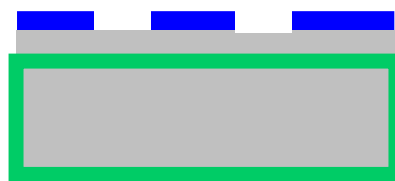
## wafer SOI



- Cleaning  
 HF 5%  
 $\text{H}_2\text{O}_2/\text{H}_2\text{SO}_4$   
 HF 5%

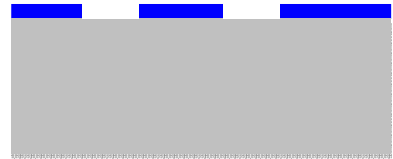
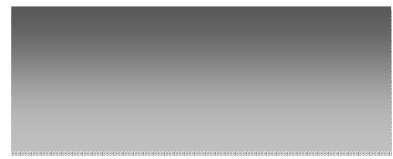


- Thick oxide growth (300 nm)



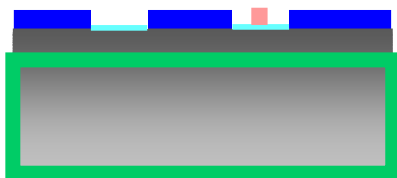
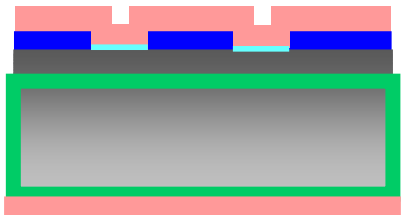
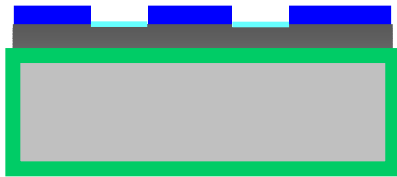
- Photolithography  
 via opening  
 windows mask  
 and wet etching

## wafer Si



## wafer SOI

*MEMS pressure sensor*      *MOS transistor* •



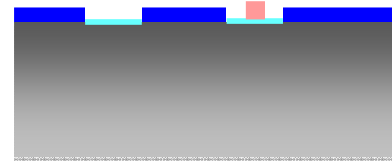
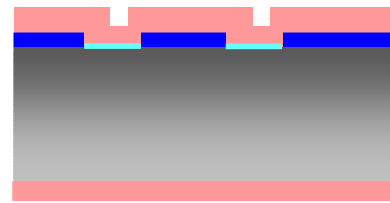
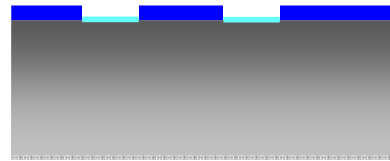
Thin oxide  
growth (450 Å,  
dry oxidation  
at 1050° C )

• Poly-silicon  
CVD (250 nm)

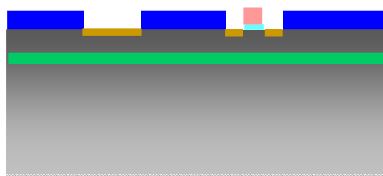
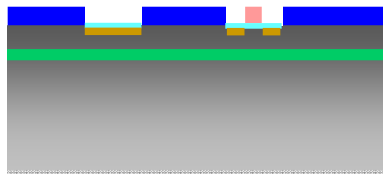
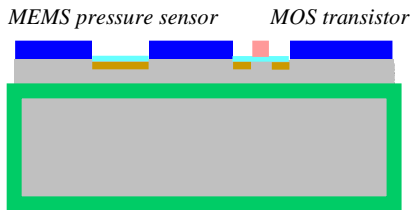
• Poly silicon  
photo  
lithography  
(mask Poly) +  
RIE on both  
sides

## wafer Si

*MEMS pressure sensor*      *MOS transistor*

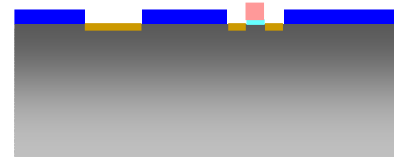
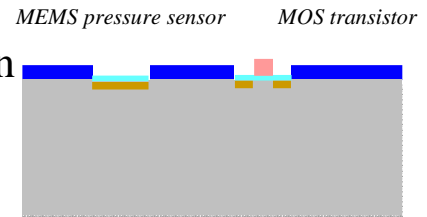


## wafer SOI



*MEMS pressure sensor*      *MOS transistor*

## wafer Si



*MEMS pressure sensor*      *MOS transistor*

- Ion implantation  
 $3.10^{E15}$  at/cm<sup>2</sup>  
@ 70keV

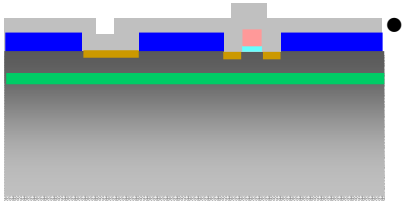
- for SOI wafer :  
Resist Spin  
coating + back-  
side Oxide  
Etching  
+ stripping

- Annealing  
(950° C, 20 min,  
nitrogen  
atmosphere)

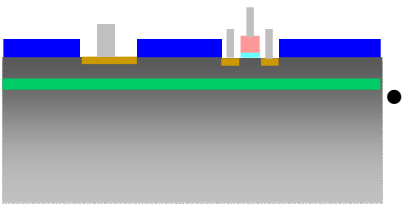
- Thin oxide  
etching

## wafer SOI

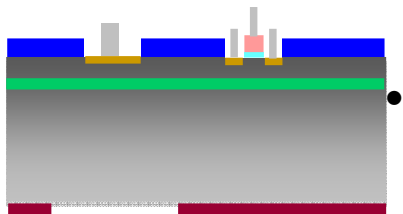
*MEMS pressure sensor*      *MOS transistor*



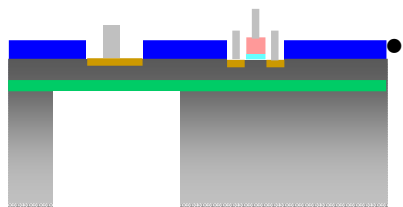
Aluminum sputtering



Aluminum photolithography + wet etch



Back side photolithography



*MEMS pressure sensor*      *MOS transistor*

DRIE on SOI wafer + photoresist stripping

## wafer Si

*MEMS pressure sensor*      *MOS transistor*

